

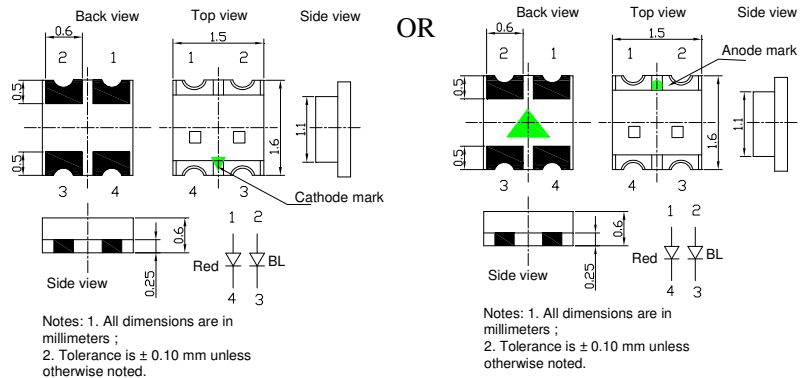
**■Features**

- Bi-Color
- Super high brightness of surface mount LED
- Water Clear Flat Mold
- Compact package outline  
(LxWxT) of 1.6mm x 1.5mm x 0.6mm
- Compatible to IR reflow soldering.

**■Applications**

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

**■Outline Dimension**



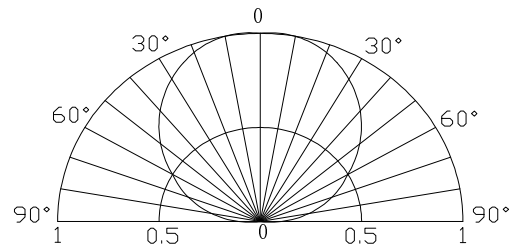
**■Absolute Maximum Rating**

(Ta=25°C)

Item	Symbol	Value		Unit
		Red	Blue	
DC Forward Current	I <sub>F</sub>	30	20	mA
Pulse Forward Current*	I <sub>FP</sub>	100	100	mA
Reverse Voltage	V <sub>R</sub>	5	5	V
Power Dissipation	P <sub>D</sub>	78	72	mW
Operating Temperature	T <sub>opr</sub>	-40 ~ +85		°C
Storage Temperature	T <sub>stg</sub>	-40~ +85		°C
Lead Soldering Temperature	T <sub>sol</sub>	260°C/10sec		-

\*Pulse width Max 0.1ms, Duty ratio max 1/10

**■Directivity**



**■Electrical -Optical Characteristics**

(Ta=25°C)

Part Number	Color		V <sub>F</sub> (V)			I <sub>R</sub> (μA)	I <sub>v</sub> (mcd)			λ <sub>D</sub> (nm)			2θ1/2(deg)
			Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.
			I <sub>F</sub> =5mA			V <sub>R</sub> =5V	I <sub>F</sub> =5mA						
OSRB0603C1C	Red	HR	1.6	2.0	2.4	10	-	40	-	620	630	640	120
	Blue	BL	2.6	3.0	3.4	10	-	20	-	460	465	475	120

\*1 Tolerance of measurements of dominant wavelength is ±1nm

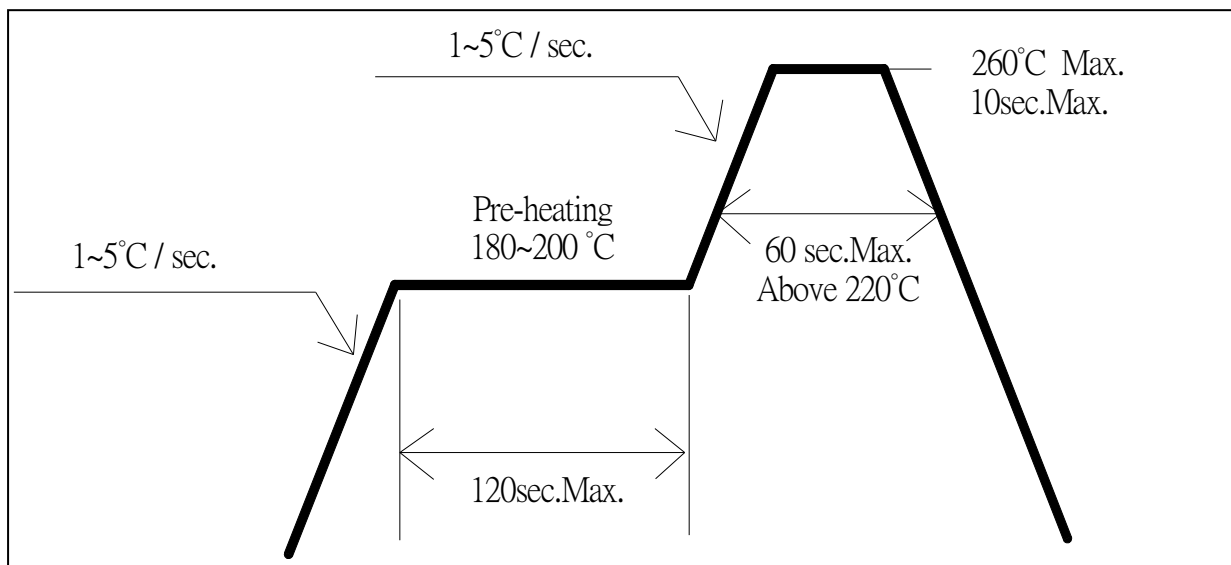
\*2 Tolerance of measurements of luminous intensity is ±15%

\*3 Tolerance of measurements of forward voltage is±0.1V

■ Soldering Conditions

Reflow Soldering		Hand Soldering	
Pre-Heat	180 ~ 200°C	Temperature Soldering time	350°C Max. 3 sec. Max. (one time only)
Pre-Heat Time	120 sec. Max.		
Peak temperature	260°C Max.		
Dipping Time	<b>10 sec. Max.</b>		
Condition	Refer to Temperature-profile		

• Reflow Soldering Condition(Lead-free Solder)



\*Recommended soldering conditions vary according to the type of LED

\*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.

\*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

• All SMD LED products are pb-free soldering available.

• Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.

• Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

• Reflow soldering should not be done more than two times.

• When soldering, do not put stress on the LEDs during heating.

• After soldering, do not warp the circuit board.